

T-43-21

CD4000UB, CD4001UB, CD4002UB, CD4025UB Types

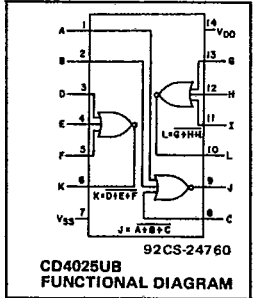
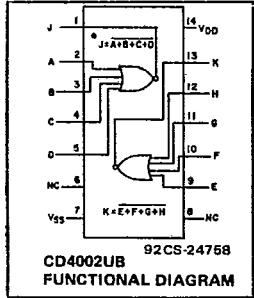
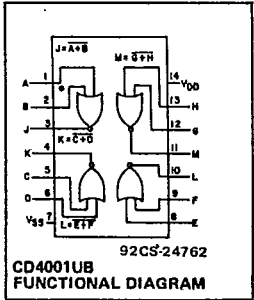
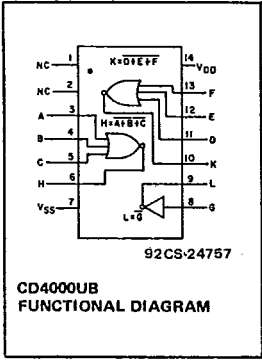
CMOS NOR Gates

High-Voltage Types (20-Volt Rating)
Dual 3 Input
plus Inverter—CD4000UB
Quad 2 Input—CD4001UB
Dual 4 Input—CD4002UB
Triple 3 Input—CD4025UB

RCA-CD4000UB, CD4001UB, CD4002UB, and CD4025UB NOR gates provide the system designer with direct implementation of the NOR function and supplement the existing family of CMOS gates.

The CD4000UB, CD4001UB, CD4002UB, and CD4025UB types are supplied in 14-lead hermetic dual-in-line ceramic packages (D and F suffixes), 14-lead dual-in-line plastic packages (E suffix), 14-lead ceramic flat packages (K suffix), and in chip form (H suffix).

- Features:
- Propagation delay time = 30 ns (typ.) at $C_L = 50$ pF, $V_{DD} = 10$ V
 - Standardized symmetrical output characteristics
 - 100% tested for maximum quiescent current at 20 V
 - Meets all requirements of JEDEC Tentative Standard No. 13A, "Standard Specifications for Description of 'B' Series CMOS Devices"
 - Maximum input current of 1 μ A at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
 - 5-V, 10-V, and 15-V parametric ratings



STATIC ELECTRICAL CHARACTERISTICS

CHARACTER- ISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
				Values at -55, +25, +125 Apply to D, F, K, H Packages Values at -40, +25, +85 Apply to E Package							
	V _O (V)	V _{IN} (V)	V _{DD} (V)	-55	-40	+85	+125	+25			
								Min.	Typ.	Max.	
Quiescent Device Current, I _{DD} Max.	—	0.5	5	0.25	0.25	7.5	7.5	—	0.01	0.25	μA
	—	0.10	10	0.5	0.5	15	15	—	0.01	0.5	
	—	0.15	15	1	1	30	30	—	0.01	1	
	—	0.20	20	5	5	150	150	—	0.02	5	
Output Low (Sink) Current I _{OL} Min.	0.4	0.5	5	0.64	0.61	0.42	0.36	0.51	1	—	mA
	0.5	0.10	10	1.6	1.5	1.1	0.9	1.3	2.6	—	
	1.5	0.15	15	4.2	4	2.8	2.4	3.4	6.8	—	
Output High (Source) Current, I _{OH} Min.	4.6	0.5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	—	mA
	2.5	0.5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	—	
	9.5	0.10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	—	
	13.5	0.15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	—	
Output Voltage: Low-Level, V _{OL} Max.	—	0.5	5	0.05				—	0	0.05	V
	—	0.10	10	0.05				—	0	0.05	
	—	0.15	15	0.05				—	0	0.05	
Output Voltage: High-Level, V _{OH} Min.	—	0.5	5	4.95				4.95	5	—	V
	—	0.10	10	9.95				9.95	10	—	
	—	0.15	15	14.95				14.95	15	—	
Input Low Voltage, V _{IL} Max.	0.5, 4.5	—	5	1				—	—	1	V
	1, 9	—	10	2				—	—	2	
	1.5, 13.5	—	15	2.5				—	—	2.5	
Input High Voltage, V _{IH} Min.	0.5	—	5	4				4	—	—	V
	1	—	10	8				8	—	—	
	1.5	—	15	12.5				12.5	—	—	
Input Current I _{IN} Max.	—	0.18	18	±0.1	±0.1	±1	±1	—	±10 ⁻⁵	±0.1	μA

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RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range (For T_A = Full Package Temperature Range)	3	18	V

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (V_{DD})
(Voltages referenced to V_{SS} Terminal) -0.5 to +20 V
INPUT VOLTAGE RANGE, ALL INPUTS -0.5 to $V_{DD} + 0.5$ V
DC INPUT CURRENT, ANY ONE INPUT ± 10 mA
POWER DISSIPATION PER PACKAGE (P_D):
For $T_A = -40$ to $+60^\circ\text{C}$ (PACKAGE TYPE E) 500 mW
For $T_A = +60$ to $+85^\circ\text{C}$ (PACKAGE TYPE E) Derate Linearly at 12 mW/ $^\circ\text{C}$ to 200 mW
For $T_A = -55$ to $+100^\circ\text{C}$ (PACKAGE TYPES D, F, K) 500 mW
For $T_A = +100$ to $+125^\circ\text{C}$ (PACKAGE TYPES D, F, K) Derate Linearly at 12 mW/ $^\circ\text{C}$ to 200 mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR
FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100 mW
OPERATING-TEMPERATURE RANGE (T_A):
PACKAGE TYPES D, F, K, H -55 to $+125^\circ\text{C}$
PACKAGE TYPE E -40 to $+85^\circ\text{C}$
STORAGE TEMPERATURE RANGE (T_{stg}) -65 to $+150^\circ\text{C}$
LEAD TEMPERATURE (DURING SOLDERING):
At distance 1/16 $\pm$ 1/32 Inch (1.59 $\pm$ 0.79 mm) from case for 10 s max. $+265^\circ\text{C}$

DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = 25^\circ\text{C}$, Input $t_r, t_f = 20$ ns, and $C_L = 50$ pF, $R_L = 200$ K Ω

CHARACTERISTIC	TEST CONDITIONS	ALL TYPES LIMITS		UNITS
		V _{DD} Volts	TYP. MAX.	
Propagation Delay Time, t _{PHL} , t _{PLH}		5	60 120	ns
		10	30 60	
		15	25 50	
Transition Time, t _{THL} , t _{TLH}		5	100 200	ns
		10	50 100	
		15	40 80	
Input Capacitance, C _{IN}	Any Input		10 15	pF

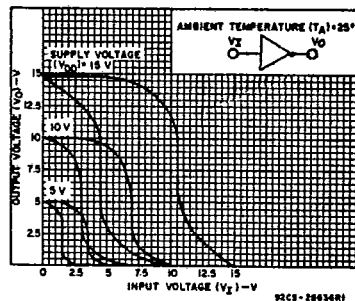


Fig. 1 - Minimum and maximum voltage transfer characteristics.

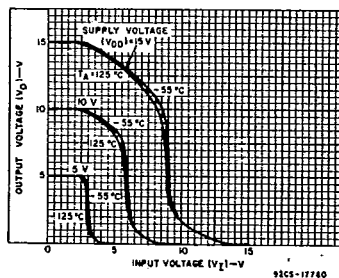


Fig. 2 - Typical voltage transfer characteristics as a function of temperature.

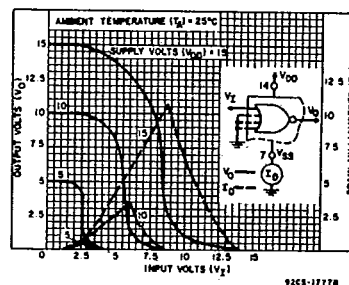


Fig. 3 - Typical current & voltage transfer characteristics.

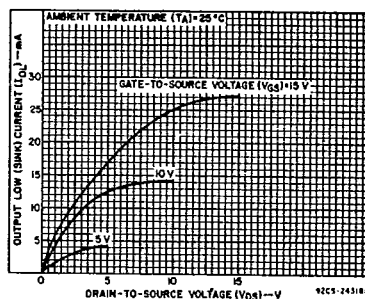


Fig. 5 - Typical output low (sink) current characteristics.

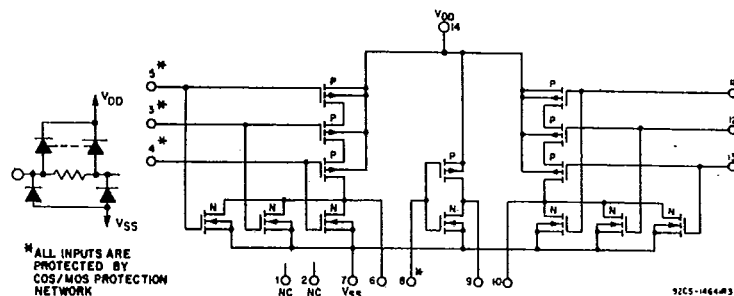


Fig. 4 - Schematic diagram for type CD4000UB.

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CD4000UB, CD4001UB, CD4002UB, CD4025UB Types

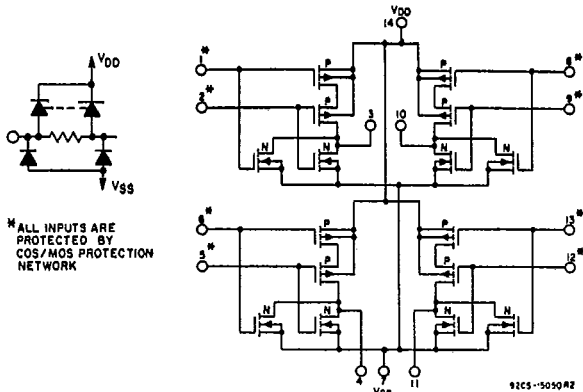


Fig. 6 - Schematic diagram for type CD4001UB.

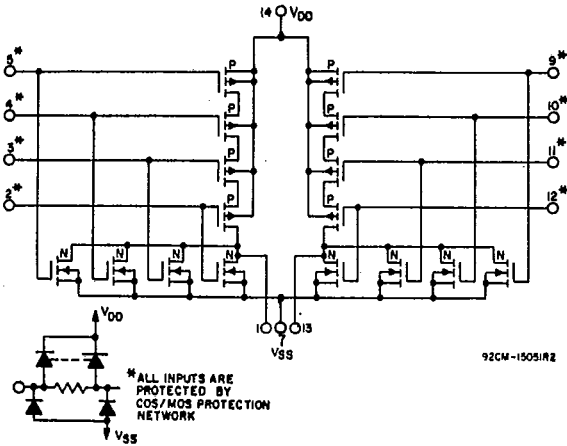


Fig. 7 - Schematic diagram for type CD4002UB.

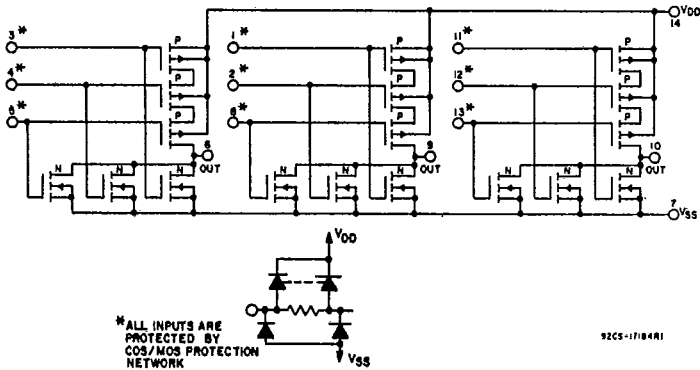


Fig. 8 - Schematic diagram for type CD4025UB.

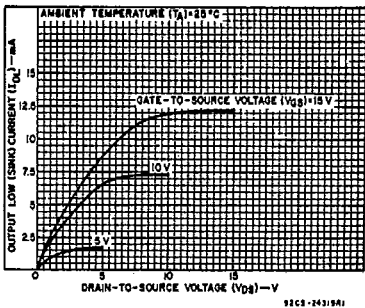


Fig. 9 - Minimum output low (sink) current characteristics.

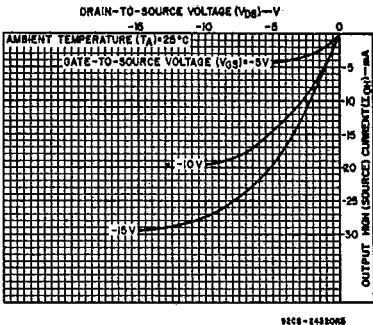


Fig. 10 - Typical output high (source) current characteristics.

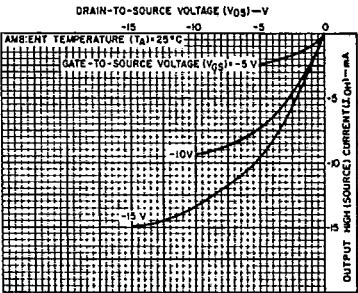


Fig. 11 - Minimum output high (source) current characteristics.

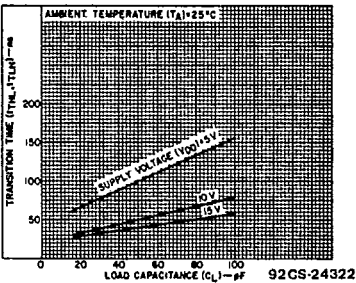


Fig. 12 - Typical transition time vs. load capacitance.

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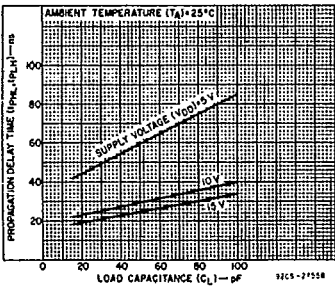


Fig. 13 - Typical propagation delay time vs. load capacitance.

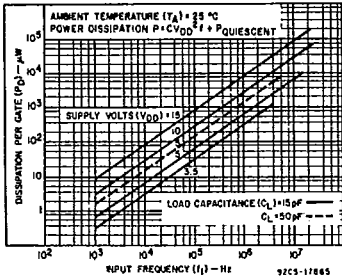


Fig. 14 - Typical power dissipation vs. frequency.

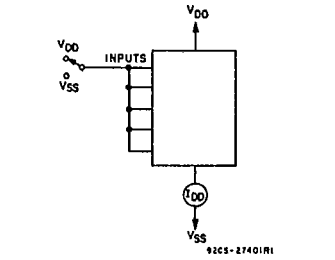


Fig. 15 - Quiescent device current test circuit.

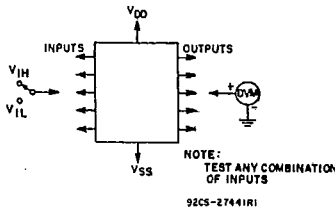


Fig. 16 - Input voltage test circuit.

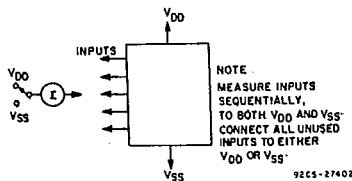
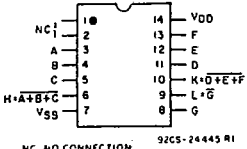
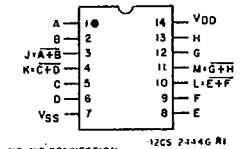


Fig. 17 - Input leakage current test circuit.

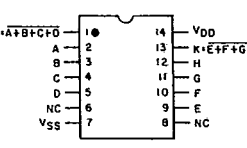
TERMINAL ASSIGNMENTS



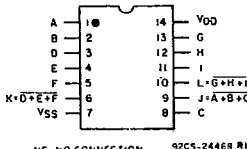
CD4000UB



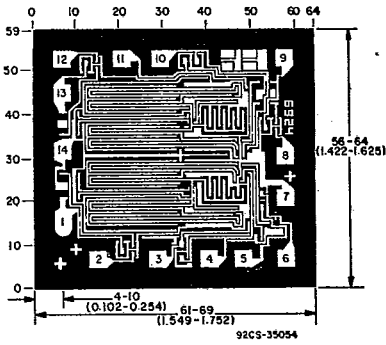
CD4001UB



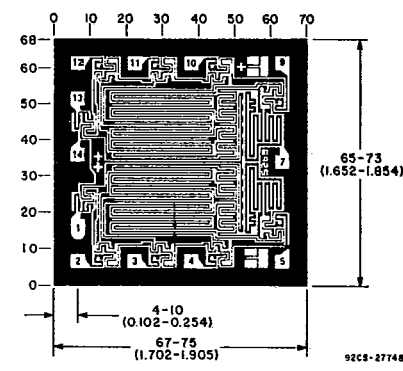
CD4002UB



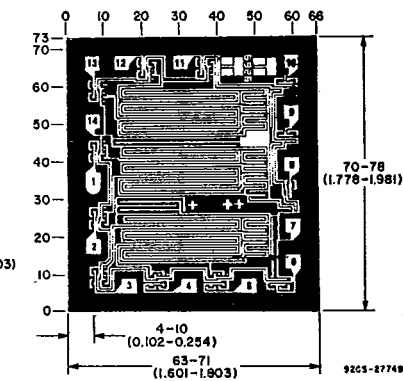
CD4025UB



CD4001UB

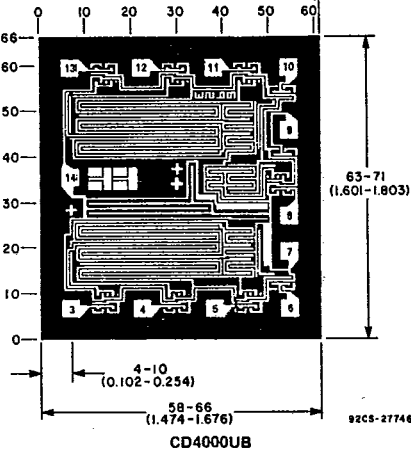


CD4002UB



CD4025UB

CHIP PHOTOGRAPHS
Dimensions and Pad Layouts



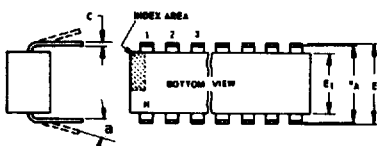
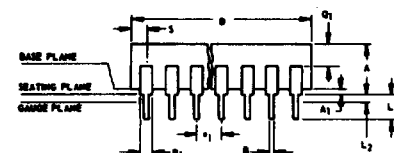
CD4000UB

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10⁻³ inch).

The photographs and dimensions of each CMOS chip represent a chip when it is part of the wafer. When the wafer is separated into individual chips, the angle of cleavage may vary with respect to the chip face for different chips. The actual dimensions of the isolated chip, therefore, may differ slightly from the nominal dimensions shown. The user should consider a tolerance of -3 mils to +16 mils applicable to the nominal dimensions shown.

Dimensional Outlines

Dual-In-Line Welded-Seal Ceramic Packages



NOTES:

Refer to Rules for Dimensioning (JEDEC Publication No. 95) for Axial Lead Product Outlines.

- When this device is supplied solder-dipped, the maximum lead thickness (narrow portion) will not exceed 0.013" (0.33 mm).
- Leads within 0.005" (0.12 mm) radius of True Position (TP) at gauge plane with maximum material condition and unit installed.
- e_A applies in zone L₂ when unit installed.
- a applies to spread leads prior to installation.
- N is the maximum quantity of lead positions.
- N₁ is the quantity of allowable missing leads.

(D) SUFFIX (JEDEC MO-001-AD)
14-Lead Dual-In-Line Welded-Seal
Ceramic Package

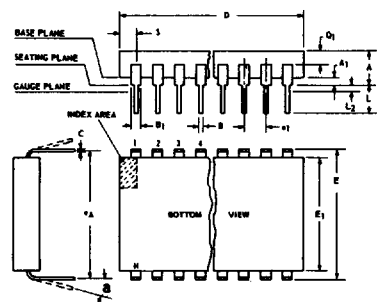
SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.120	0.160		3.05	4.06
A ₁	0.020	0.065		0.51	1.65
B	0.014	0.020		0.356	0.508
B ₁	0.060	0.065		1.27	1.65
C	0.008	0.012	1	0.204	0.304
D	0.745	0.770		18.93	19.55
E	0.300	0.325		7.62	8.25
E ₁	0.240	0.260		6.10	6.60
e ₁	0.100 TP		2	2.54 TP	
e _A	0.300 TP		2, 3	7.62 TP	
L	0.125	0.150		3.18	3.81
L ₂	0.000	0.030		0.000	0.76
a	0°	15°	4	0°	15°
N	14		5	14	
N ₁	0		6	0	
Q ₁	0.050	0.085		1.27	2.15
S	0.065	0.090		1.66	2.28

92SS-4411R2

(D) SUFFIX (JEDEC MO-001-AE)
16-Lead Dual-In-Line Welded-Seal
Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.120	0.160		3.05	4.06
A ₁	0.020	0.065		0.51	1.65
B	0.014	0.020		0.356	0.508
B ₁	0.035	0.065		0.89	1.65
C	0.008	0.012	1	0.204	0.304
D	0.745	0.785		18.93	19.93
E	0.300	0.325		7.62	8.25
E ₁	0.240	0.260		6.10	6.60
e ₁	0.100 TP		2	2.54 TP	
e _A	0.300 TP		2, 3	7.62 TP	
L	0.125	0.150		3.18	3.81
L ₂	0.000	0.030		0.000	0.76
a	0°	15°	4	0°	15°
N	16		5	16	
N ₁	0		6	0	
Q ₁	0.050	0.085		1.27	2.15
S	0.015	0.060		0.39	1.52

92SS-4266R5



NOTES:

Refer to Rules for Dimensioning (JEDEC Publication No. 95) for Axial Lead Product Outlines.

- When this device is supplied solder-dipped, the maximum lead thickness (narrow portion) will not exceed 0.013" (0.33 mm).
- Leads within 0.005" (0.12 mm) radius of True Position (TP) at gauge plane with maximum material condition and unit installed.
- e_A applies in zone L₂ when unit installed.
- a applies to spread leads prior to installation.
- N is the maximum quantity of lead positions.
- N₁ is the quantity of allowable missing leads.

(D) SUFFIX (JEDEC MO-015-AG)
24-Lead Dual-In-Line Welded-Seal
Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.090	0.200		2.29	5.08
A ₁	0.020	0.070		0.51	1.78
B	0.015	0.020		0.381	0.508
B ₁	0.045	0.055		1.143	1.397
C	0.008	0.012	1	0.204	0.304
D	1.15	1.22		29.21	30.98
E	0.600	0.625		15.24	15.87
E ₁	0.480	0.520		12.20	13.20
e ₁	0.100 TP		2	2.54 TP	
e _A	0.600 TP		2, 3	15.24 TP	
L	0.100	0.180		2.54	4.57
L ₂	0.000	0.030		0.00	0.76
a	0°	15°	4	0°	15°
N	24		5	24	
N ₁	0		6	0	
Q ₁	0.020	0.080		0.51	2.03
S	0.020	0.060		0.51	1.52

92CS-19948R4

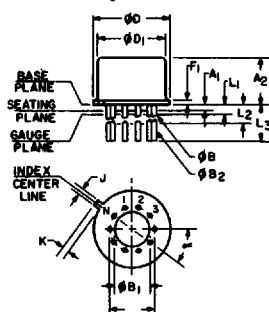
(D) SUFFIX (JEDEC MO-015-AH)
28-Lead Dual-In-Line Welded-Seal
Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.090	0.200		2.29	5.08
A ₁	0.020	0.070	2	0.51	1.77
B	0.015	0.020		0.381	0.508
B ₁	0.015	0.065		0.39	1.39
C	0.008	0.012	1	0.204	0.304
D	1.380	1.420		35.06	36.06
E	0.600	0.625		15.24	15.87
E ₁	0.485	0.515		12.32	13.08
e ₁	0.100 TP		2	2.54 TP	
e _A	0.600 TP		2, 3	15.24 TP	
L	0.100	0.200		2.54	5.08
L ₂	0.000	0.030		0.00	0.76
a	0°	15°	4	0°	15°
N	28		5	28	
N ₁	0		6	0	
Q ₁	0.020	0.070		0.51	1.77
S	0.040	0.070		1.02	1.77

92CM-20250R2

TO-5 Style Package

(T) SUFFIX (JEDEC MO-006-AG)
12-Lead Metal Package



92CS-19774

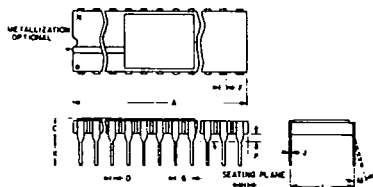
SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
a	0.230		2	5.84 TP	
A ₁	0	0		0	0
A ₂	0.165	0.185		4.19	4.70
øB	0.016	0.019	3	0.407	0.482
øB ₁	0	0		0	0
øB ₂	0.016	0.021	3	0.407	0.533
øD	0.335	0.370		8.51	9.39
øD ₁	0.305	0.335		7.75	8.50
F ₁	0.020	0.040		0.51	1.01
J	0.028	0.034		0.712	0.863
k	0.029	0.045	4	0.74	1.14
L ₁	0.000	0.050	3	0.00	1.27
L ₂	0.250	0.500	3	6.4	12.7
L ₃	0.500	0.562	3	12.7	14.27
a	30° TP			30° TP	
N	12		6	12	
N ₁	1		5	1	

NOTES:

- Refer to Rules for Dimensioning Axial Lead Product Outlines.
- Leads at gauge plane within 0.007" (0.178 mm) radius of True Position (TP) at maximum material condition.
- øB applies between L₁ and L₂. øB₂ applies between L₂ and 0.500" (12.70 mm) from seating plane. Diameter is uncontrolled in L₁ and beyond 0.500" (12.70 mm).
- Measure from Max. øD.
- N₁ is the quantity of allowable missing leads.
- N is the maximum quantity of lead positions.

Dimensional Outlines (Cont'd)

DUAL-IN-LINE SIDE-BRAZED CERAMIC PACKAGES



NOTES:

1. Leads within 0.005" (0.13 mm) radius of True Position at maximum material condition.
2. Dimension "L" to center of leads when formed parallel.
3. When this device is supplied solder-dipped, the maximum lead thickness (narrow portion) will not exceed 0.013" (0.33 mm).

(D) SUFFIX 18-Lead Dual-In-Line Side-Brazed Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.890	0.915		22.606	23.241
C	—	0.200		—	5.080
D	0.015	0.021		0.381	0.533
F	0.054	REF.	1	1.371	REF.
G	0.100	BSC	1	2.54	BSC
H	0.035	0.065		0.889	1.651
J	0.008	0.012	3	0.203	0.304
K	0.125	0.150		3.175	3.810
L	0.290	0.310	2	7.366	7.874
M	0°	15°		0°	15°
P	0.025	0.045		0.635	1.143
N	18			18	

92CS-27231R1

(D) SUFFIX 22-Lead Dual-In-Line Side-Brazed Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	1.065	1.100		27.05	27.94
C	0.085	0.145		2.16	3.68
D	0.017	0.023		0.43	0.58
F	0.040	REF.	1	1.02	REF.
G	0.100	BSC	1	2.54	BSC
H	0.030	0.070		0.76	1.78
J	0.008	0.012	3	0.20	0.30
K	0.125	0.175		3.18	4.45
L	0.380	0.420	2	9.65	10.67
M	—	7°		—	7°
P	0.025	0.050		0.64	1.27
N	22			22	

92CS-25186R2

(D) SUFFIX 24-Lead Dual-In-Line Side-Brazed Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	1.180	1.220		29.98	30.98
C	0.085	0.145		2.16	3.68
D	0.015	0.023		0.39	0.58
F	0.040	REF.		1.02	REF.
G	0.100	BSC	1	2.54	BSC
H	0.030	0.070		0.77	1.77
J	0.008	0.012	3	0.21	0.30
K	0.125	0.175		3.18	4.44
L	0.580	0.620	2	14.74	15.74
M	—	7°		—	7°
P	0.025	0.050		0.64	1.27
N	24			24	

92CS-30986R1

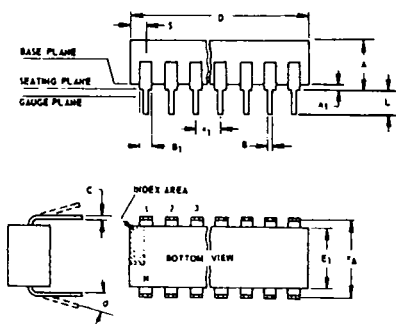
(D) SUFFIX 40-Lead Dual-In-Line Side-Brazed Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	1.980	2.020		50.30	51.30
C	0.095	0.155		2.43	3.93
D	0.017	0.023		0.43	0.58
F	0.050	REF.		1.27	REF.
G	0.100	BSC	1	2.54	BSC
H	0.030	0.070		0.76	1.78
J	0.008	0.012	3	0.20	0.30
K	0.125	0.175		3.18	4.45
L	0.580	0.620	2	14.74	15.74
M	—	7°		—	7°
P	0.025	0.050		0.64	1.27
N	40			40	

92CM-27029R2

Dual-In-Line Plastic and Frit-Seal Ceramic Packages

(E) SUFFIX (JEDEC MO-001-AN) 8-Lead Dual-In-Line Plastic (Mini-DIP) Package



SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.155	0.200		3.94	5.08
A ₁	0.020	0.050		0.508	1.27
B	0.014	0.020		0.356	0.508
B ₁	0.035	0.065		0.889	1.65
C	0.008	0.012	1	0.203	0.304
D	0.370	0.400		9.40	10.16
E	0.300	0.325		7.62	8.25
E ₁	0.240	0.260		6.10	6.60
e ₁	0.100	TP	2	2.54	TP
e _A	0.300	TP	2, 3	7.62	TP
L	0.125	0.150		3.18	3.81
L ₂	0.000	0.030		0.000	0.762
a	0	15	4	0	15
N	8		5	8	
N ₁	0		6	0	
O ₁	0.040	0.075		1.02	1.90
S	0.015	0.060		0.381	1.52

92CS-24026 R1

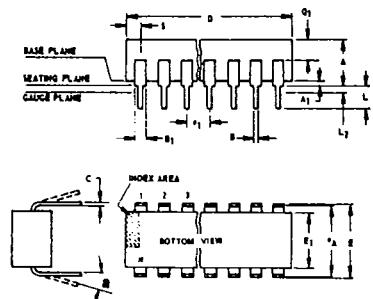
NOTES:

Refer to Rules for Dimensioning (JEDEC Publication No. 95) for Axial Lead Product Outlines.

1. When this device is supplied solder-dipped, the maximum lead thickness (narrow portion) will not exceed 0.013".
2. Leads within 0.005" (0.12 mm) radius of True Position (TP) at gauge plane with maximum material condition and unit installed.
3. e_A applies in zone L₂ when unit installed.
4. a applies to spread leads prior to installation.
5. N is the maximum quantity of lead positions.
6. N₁ is the quantity of allowable missing leads.

Dimensional Outlines (Cont'd)

Dual-In-Line Plastic and Frit-Seal Ceramic Packages (Cont'd)



NOTES:

Refer to Rules for Dimensioning (JEDEC Publication No. 95) for Axial Lead Product Outlines.

- When this device is supplied solder dipped, the maximum lead thickness (narrow portion) will not exceed 0.013" (0.33 mm).
- Leads within 0.005" (0.12 mm) radius of True Position (TP) at gauge plane with maximum material condition and unit installed.
- e_1 applies in zone L₂ when unit installed.
- a applies to spread leads prior to installation.
- N is the maximum quantity of lead positions.
- N_1 is the quantity of allowable missing leads.

(E) and (F) SUFFIXES (JEDEC MO-001-AB)
14-Lead Dual-In-Line Plastic or
Frit-Seal Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.155	0.200		3.94	5.08
A ₁	0.020	0.060		0.51	1.27
B	0.014	0.020		0.356	0.508
B ₁	0.060	0.065		1.27	1.65
C	0.008	0.012	1	0.204	0.304
D	0.745	0.770		18.93	19.55
E	0.300	0.325		7.62	8.25
E ₁	0.240	0.260		6.10	6.60
e_1	0.100 TP		2	2.54 TP	
e_A	0.300 TP		2, 3	7.62 TP	
L	0.125	0.150		3.18	3.81
L ₂	0.000	0.030		0.000	0.76
a	0°	15°	4	0°	15°
N	14	5	14		
N ₁	0	6	0		
Q ₁	0.040	0.075		1.02	1.90
S	0.065	0.090		1.66	2.28

92SS-4296R3

(E) and (F) SUFFIXES (JEDEC MO-001-AC)
16-Lead Dual-In-Line Plastic or
Frit-Seal Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.155	0.200		3.94	5.08
A ₁	0.020	0.050		0.51	1.27
B	0.014	0.020		0.356	0.508
B ₁	0.035	0.065		0.89	1.65
C	0.008	0.012	1	0.204	0.304
D	0.745	0.785		18.93	19.93
E	0.300	0.325		7.62	8.25
E ₁	0.240	0.260		6.10	6.60
e_1	0.100 TP		2	2.54 TP	
e_A	0.300 TP		2, 3	7.62 TP	
L	0.125	0.150		3.18	3.81
L ₂	0.000	0.030		0.000	0.76
a	0°	15°	4	0°	15°
N	16	5	16		
N ₁	0	6	0		
Q ₁	0.040	0.075		1.02	1.90
S	0.015	0.060		0.39	1.52

92CM-15967R4

(E) SUFFIX
18-Lead Dual-In-Line
Plastic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.155	0.200		3.94	5.08
A ₁	0.020	0.060		0.508	1.27
B	0.014	0.020		0.356	0.508
B ₁	0.035	0.065		0.89	1.65
C	0.008	0.012	1	0.204	0.304
D	0.845	0.885		21.47	22.47
E ₁	0.240	0.260		6.10	6.60
e_1	0.100 TP		2	2.54 TP	
e_A	0.300 TP		2, 3	7.62 TP	
L	0.125	0.150		3.18	3.81
a	0°	15°	4	0°	15°
N	18	5	18		
N ₁	0	6	0		
S	0.015	0.060		0.39	1.52

92CS-30630

(E) SUFFIX
22-Lead Dual-In-Line
Plastic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.155	0.200		3.94	5.08
A ₁	0.020	0.050		0.508	1.27
B	0.015	0.020		0.381	0.508
B ₁	0.035	0.065		0.89	1.65
C	0.008	0.012	1	0.204	0.304
D		1.120			28.44
E	0.390	0.420		9.91	10.66
E ₁	0.345	0.355		8.77	9.01
e_1	0.100 TP		2	2.54 TP	
e_A	0.400 TP		2, 3	10.16 TP	
L	0.125	0.150		3.18	3.81
L ₂	0	0.030		0	0.762
a	2°	15°	4	2°	15°
N	22	5	22		
N ₁	0	6	0		
Q ₁	0.065	0.085		1.40	2.15
S	0.015	0.060		0.381	1.27

92CS-30830

(F) SUFFIX (JEDEC MO-001-AG)
16-Lead Dual-In-Line
Frit-Seal Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.165	0.210		4.20	5.33
A ₁	0.015	0.045		0.381	1.14
B	0.015	0.020		0.381	0.508
B ₁	0.045	0.070		1.15	1.77
C	0.009	0.011	1	0.229	0.279
D	0.750	0.795		19.05	20.19
E	0.295	0.325		7.50	8.25
E ₁	0.245	0.300		6.23	7.62
e_1	0.100 TP		2	2.54 TP	
e_A	0.300 TP		2, 3	7.62 TP	
L	0.120	0.160		3.05	4.06
L ₂	0.000	0.030		0.000	0.76
a	2°	15°	4	2°	15°
N	16	5	16		
N ₁	0	6	0		
Q ₁	0.050	0.080		1.27	2.03
S	0.010	0.060		0.254	1.52

92CM-22284R1

(E) and (F) SUFFIXES (JEDEC MO-015-AA)
24-Lead Dual-In-Line Plastic or
Frit-Seal Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.120	0.250		3.10	6.30
A ₁	0.020	0.070		0.51	1.77
B	0.016	0.020		0.407	0.508
B ₁	0.028	0.070		0.72	1.77
C	0.008	0.012	1	0.204	0.304
D	1.20	1.29		30.48	32.76
E	0.600	0.625		15.24	15.87
E ₁	0.515	0.580		13.09	14.73
e_1	0.100 TP		2	2.54 TP	
e_A	0.600 TP		2, 3	15.24 TP	
L	0.100	0.200		2.54	5.00
L ₂	0.000	0.030		0.00	0.76
a	0°	15°	4	0°	15°
N	24	5	24		
N ₁	0	6	0		
Q ₁	0.040	0.075		1.02	1.90
S	0.040	0.100		1.02	2.54

92CS26938R2

(E) SUFFIX
40-Lead Dual-In-Line
Plastic Package

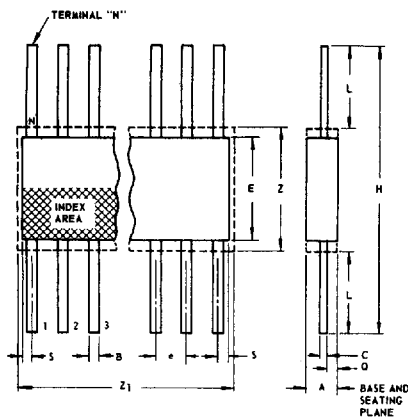
SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.120	0.250		3.10	6.30
A ₁	0.020	0.070		0.51	1.77
B	0.016	0.020		0.407	0.508
B ₁	0.028	0.070		0.72	1.77
C	0.008	0.012	1	0.204	0.304
D	2.000	2.090		50.80	53.09
E ₁	0.515	0.580		13.09	14.73
e_1	0.100 TP		2	2.54 TP	
e_A	0.600 TP		2, 3	15.24 TP	
L	0.100	0.200		2.54	5.00
L ₂	0.000	0.030		0.00	0.76
a	0°	15°	4	0°	15°
N	40	5	40		
N ₁	0	6	0		
Q ₁	0.065	0.095		1.66	2.41
S	0.040	0.100		1.02	2.54

92CS-30959

Dimensional Outlines (Cont'd)

Ceramic Flat Packs

(K) SUFFIX (JEDEC MO-004-AF) 14-Lead



SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.008	0.100		0.21	2.54
B	0.015	0.019	1	0.381	0.482
C	0.003	0.006	1	0.077	0.152
e	0.050 TP		2	1.27 TP	
E	0.200	0.300		5.1	7.6
H	0.600	1.000		15.3	25.4
L	0.150	0.350		3.9	8.8
N	14		3	14	
Q	0.005	0.050		0.13	1.27
S	0.000	0.050		0.00	1.27
Z	0.300		4	7.62	
Z1	0.400		4	10.16	

92S8-4300R3

NOTES:

1. Refer to JEDEC Publication No. 95 for Rules for Dimensioning Peripheral Lead Outlines.
2. Leads within 0.005" (0.12 mm) radius of True Position (TP) at maximum material condition.
3. N is the maximum quantity of lead positions.
4. Z and Z1 determine a zone within which all body and lead irregularities lie.

(K) SUFFIX (JEDEC MO-004-AG) 16-Lead

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.008	0.100		0.21	2.54
B	0.015	0.019	1	0.381	0.482
C	0.003	0.006	1	0.077	0.152
e	0.050 TP		2	1.27 TP	
E	0.200	0.300		5.1	7.6
H	0.600	1.000		15.3	25.4
L	0.150	0.350		3.9	8.8
N	16		3	16	
Q	0.005	0.050		0.13	1.27
S	0.000	0.025		0.00	0.63
Z	0.300		4	7.62	
Z1	0.400		4	10.16	

92CS-17271R3

(K) SUFFIX 24-Lead

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.075	0.120		1.91	3.04
B	0.018	0.022	1	0.458	0.558
C	0.004	0.007	1	0.102	0.177
e	0.050 TP		2	1.27 TP	
E	0.600	0.700		15.24	17.78
H	1.150	1.350		29.21	34.29
L	0.225	0.325		5.72	8.25
N	24		3	24	
Q	0.035	0.070		0.89	1.77
S	0.060	0.110	1	1.53	2.79
Z	0.700		4	17.78	
Z1	0.750		4	19.05	

92CS-19949R2

(K) SUFFIX 28-Lead

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.075	0.120		1.91	3.04
B	0.018	0.022	1	0.458	0.558
C	0.004	0.007	1	0.102	0.177
e	0.050 TP		2	1.27 TP	
E	0.600	0.700		15.24	17.78
H	1.150	1.350		29.21	34.29
L	0.225	0.325		5.72	8.25
N	28		3	28	
Q	0.035	0.070		0.89	1.77
S	0	0.060	1	0	1.53
Z	0.700		4	17.78	
Z1	0.750		4	19.05	

92CS-20972